

## 21<sup>th</sup> IC & SENSOR PACKAGING TECHNOLOGY EXPO

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It is our great pleasure to inform you that we will be introducing our products during the upcoming 21<sup>th</sup> IC & SENSOR PACKAGING TECHNOLOGY EXPO (Jan. 15 - 17, 2020) in Tokyo, Japan. At this Exhibition, visitors will be able to see an exhibition of our new product lineup and demonstration of their products. Those who are coming to the exhibition are encouraged to please visit our booth. We are looking forward to seeing you at this exhibition.

Please see the below brief description of the product line that will be introduced during this exhibition.

|                  |  |  |
|------------------|--|--|
| Dates            | Jan. 15[Wed]-17[Fri], 2020 10:00 – 18:00 (Last day until 17:00)  |  |
| Venue            | Tokyo Big Sight, Tokyo, Japan West Hall  |  |
| Booth No.        | W9-20  |  |
| Access           | <a href="http://www.bigsight.jp/english/hotel/transportation/">http://www.bigsight.jp/english/hotel/transportation/</a>                          |  |
| Exhibit Products | <p>Die Bonder for IC,SENSOR<br/><b>BESTEM- D310plus+</b></p>  | <p>Wire Bonding Inspection Equipment<br/>(Desktop machine)<br/><b>BESTEM-V110</b></p>  |

For any inquiries, please contact us:

Canon machinery Inc. SEMICON SYSTEM BUSINESS HQ / SALES DIVISION

Tel : +81 77 566 1822 Fax : +81 77 566 1833

E-Mail : [cmi-sales-ml@mail.canon](mailto:cmi-sales-ml@mail.canon)